

Title (en)
Thermal plate

Title (de)
Wärmeplatte

Title (fr)
Plaque thermique

Publication
EP 2338594 A1 20110629 (EN)

Application
EP 09180560 A 20091223

Priority
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Abstract (en)
The present invention relates to a thermal plate for heating and/or cooling several caps comprising a base plate of thermally conducting material; several receptacles for caps being in thermal contact with the base plate; a support structure for supporting the receptacles being in thermal contact with the base plate; and means for heating and/or cooling the base plate, wherein the support structure together with the base plate provides a substantially closed hollow space surrounding the receptacles.

IPC 8 full level
B01L 3/00 (2006.01); **B01L 7/00** (2006.01)

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